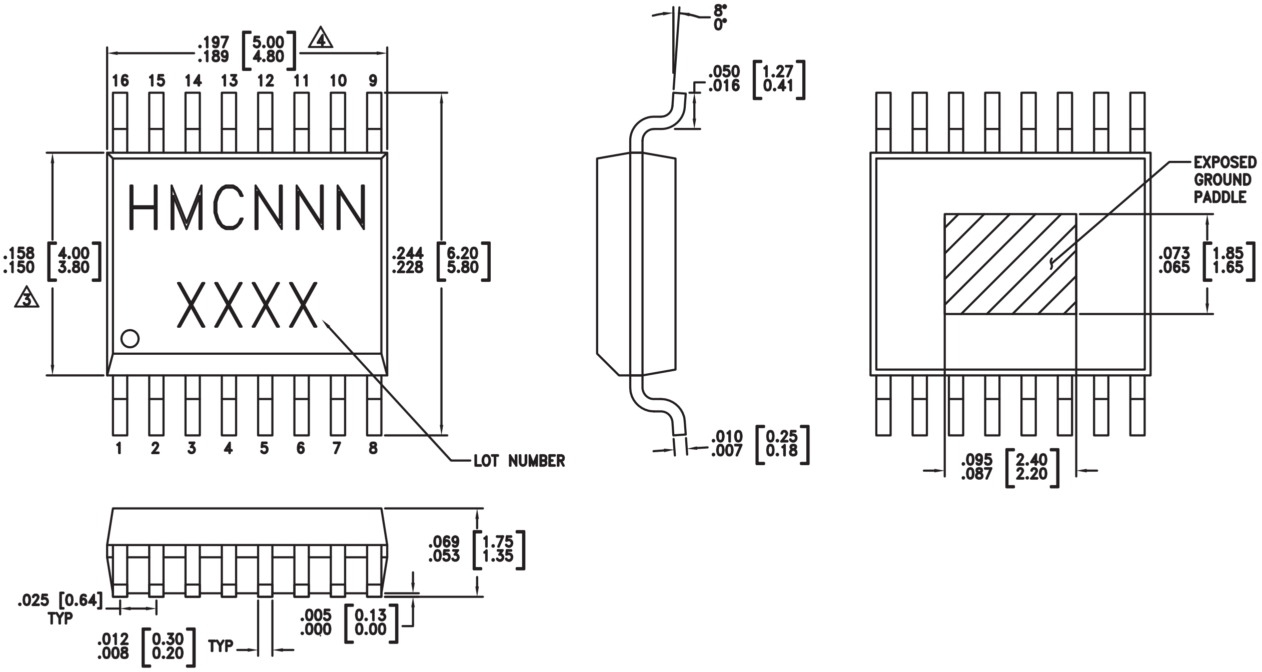
QS16G (E) – 16 LEAD PLASTIC QSOP PACKAGE WITH EXPOSED BASE

QS16G (E) Package Outline Drawing



NOTES:

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
QS16G	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HMCNNN XXXX
QS16GE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HMCNNN XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

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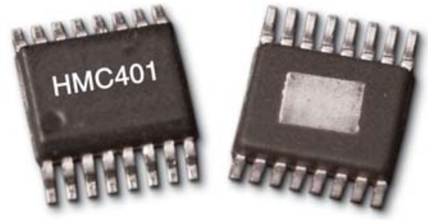
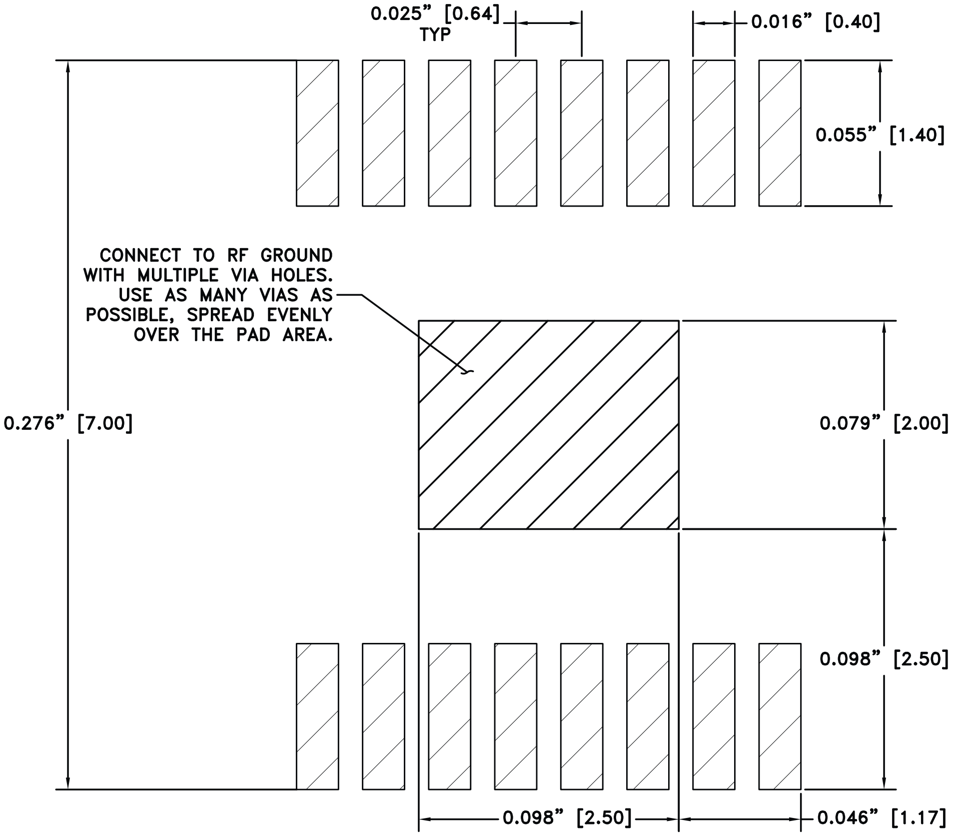
Suggested QS16G (E) PCB Land Pattern





NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.